

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

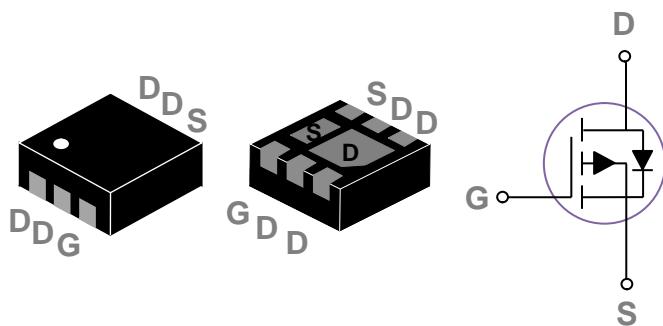
- -15V,-8.5A, RDS(ON) = $25m\Omega$ @VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications
- Marking : IA

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

BVDSS	RDS(ON)	ID
-15V	25mΩ	-8.5A

DFN2x2-6L Pin Configuration



Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-15	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	-8.5	A
	Drain Current – Continuous ($T_c=100^\circ C$)	-5.4	A
I_{DM}	Drain Current – Pulsed ¹	-34	A
P_D	Power Dissipation ($T_c=25^\circ C$)	3.3	W
	Power Dissipation – Derate above $25^\circ C$	0.026	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R_{JA}	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
R_{JC}	Thermal Resistance Junction to Case	---	38	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$		-15	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.02	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-13\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-13\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	23	25	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	27	37	
		$V_{\text{GS}}=-1.8\text{V}$, $I_{\text{D}}=-2\text{A}$	---	33	45	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.6	-1	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	2	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{S}}=-3\text{A}$	---	8.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	16.1	25	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.8	3	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	3.8	7	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=25\Omega$	---	8.2	16	nS
T_r	Rise Time ^{2,3}		---	30	57	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	71.1	135	
T_f	Fall Time ^{2,3}		---	19.8	38	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	1440	2100	pF
C_{oss}	Output Capacitance		---	155	230	
C_{rss}	Reverse Transfer Capacitance		---	115	170	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-8.5	A
I_{SM}	Pulsed Source Current		---	---	-17	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

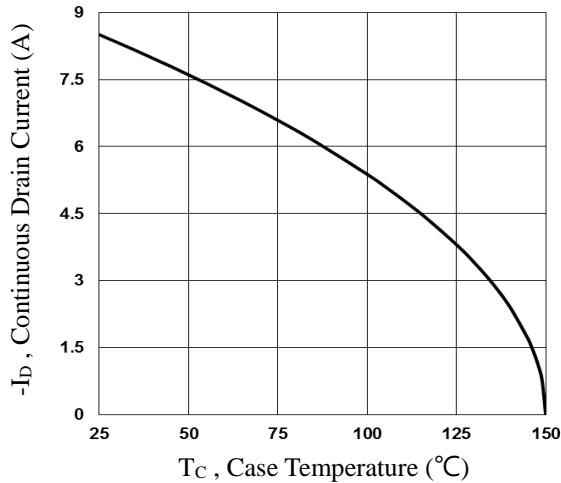


Fig.1 Continuous Drain Current vs. T_C

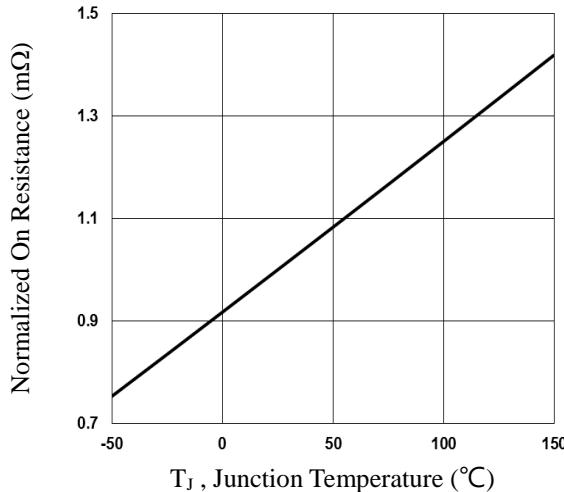


Fig.2 Normalized RDSON vs. T_J

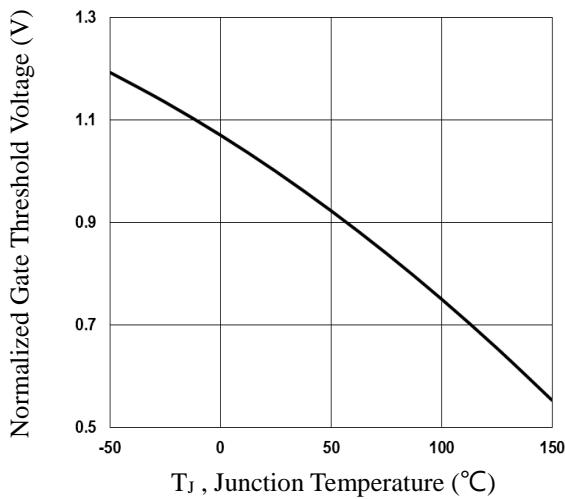


Fig.3 Normalized V_{th} vs. T_J

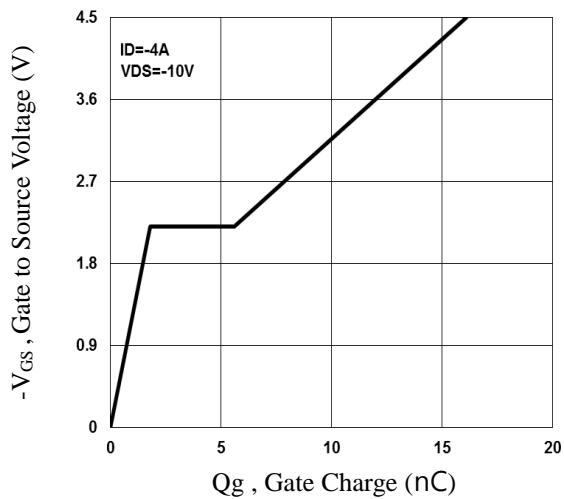


Fig.4 Gate Charge Waveform

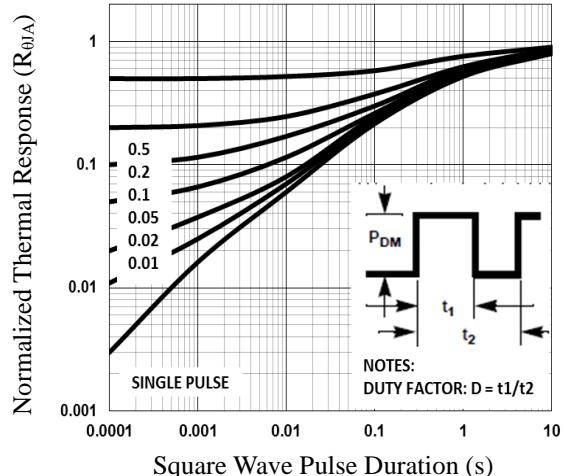


Fig.5 Normalized Transient Impedance

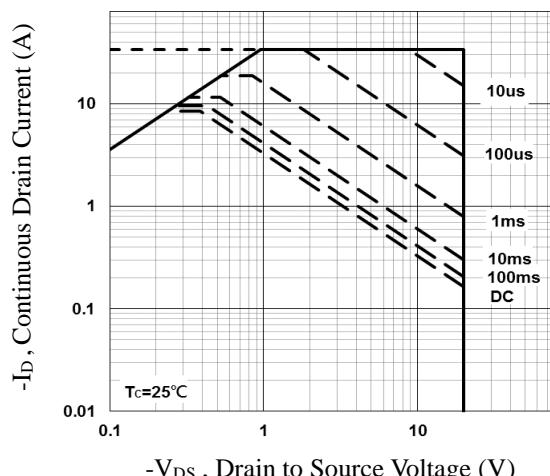


Fig.6 Maximum Safe Operation Area

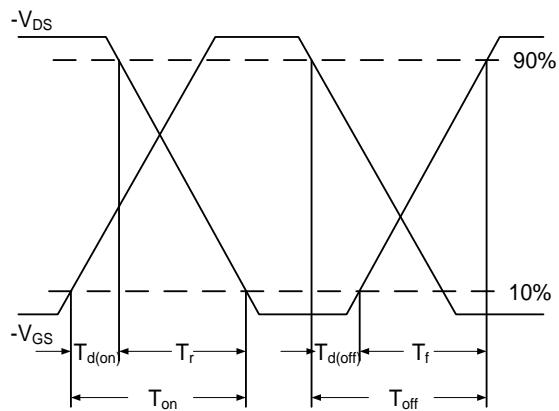


Fig.7 Switching Time Waveform

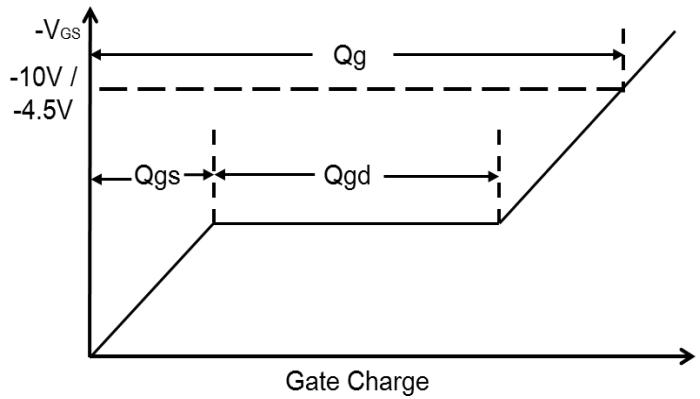
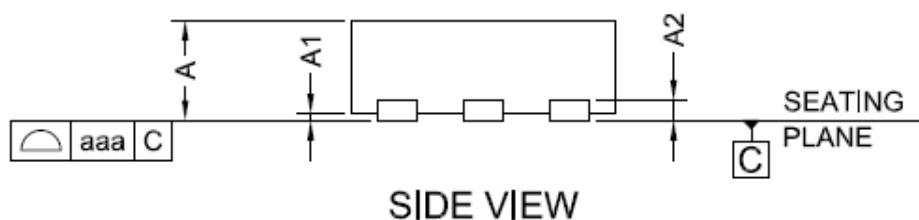
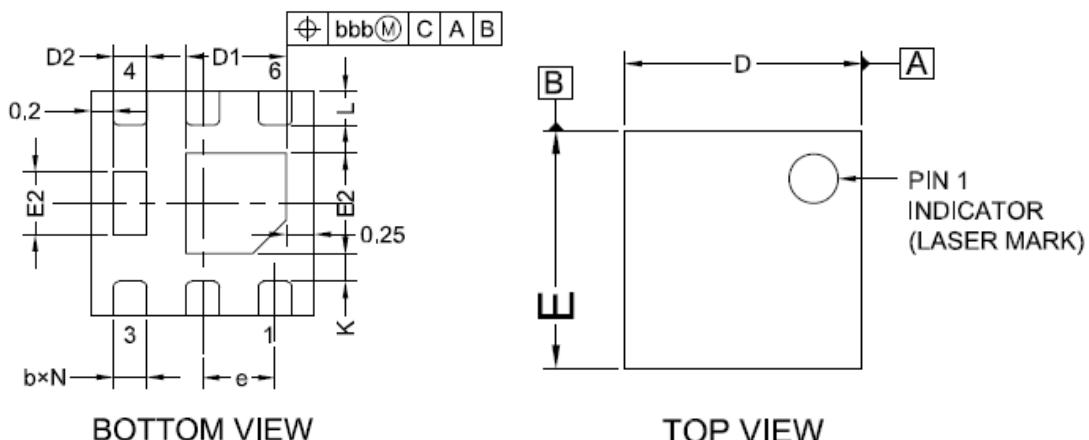


Fig.8 Gate Charge Waveform

DFN2x2-6L PACKAGE INFORMATION



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2 0.152REF.			
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.80	0.90	1.00
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.80	0.90	1.00
E2	0.46	0.56	0.66
e	0.65BSC		
L	0.25	0.30	0.35
J	0.40BSC		
K	0.20MIN		
N	6		
aaa	0.08		
bbb	0.10		

单击下面可查看定价，库存，交付和生命周期等信息

[>>SHIKUES\(时科\)](#)